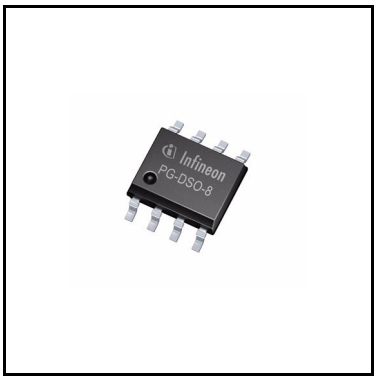
TLE9351SJ

High speed CAN FD transceiver



Features

- Fully compliant to ISO 11898-2:2016 and SAE J2284-4/-5
- Loop delay symmetry for CAN FD data frames up to 5 MBit/s
- Certified according to VeLIO (Vehicle LAN Interoperability and Optimization) test requirements
- Very low electromagnetic emission (EME) allows the use without additional common mode choke
- Bus wake-up pattern (WUP) function with optimized filter time for worldwide OEM usage
- Stand-by mode with minimized quiescent current
- Excellent ESD robustness
- TxD time-out function
- Very low CAN bus leakage current in power-down state
- Overtemperature protection
- Protected against automotive transients according to ISO 7637 and SAE J2962-2
- Green Product (RoHS compliant)

Potential applications

- Engine control units (ECU)
- Gateway modules
- Body control modules (BCM)

Product validation

Qualified for automotive applications. Product validation according to AEC-Q100.

Description

The TLE9351SJ is a high speed CAN transceiver, used in HS CAN systems for automotive applications as well as for industrial applications. It is designed to fulfill the requirements of ISO 11898-2:2016 physical layer specification as well as SAE J1939 and SAE J2284.

The TLE9351SJ is available in a RoHS compliant, halogen free PG-DSO-8 package.

As an interface between the physical bus layer and the HS CAN protocol controller, the TLE9351SJ is designed to protect the microcontroller against interferences generated inside the network. A very high ESD robustness

and the optimized RF immunity allows the use in automotive applications without additional protection devices, such as suppressor diodes or common mode chokes.

Based on the high symmetry of the CANH and CANL output signals, the TLE9351SJ provides a very low level of electromagnetic emission (EME) within a wide frequency range. The TLE9351SJ fulfills even stringent EMC test limits without an additional external circuit, such as a common mode choke.

The optimized transmitter symmetry combined with the optimized delay symmetry of the receiver enables the TLE9351SJ to support CAN FD data frames. The device supports data transmission rates up to 5 MBit/s, depending on the size of the network and the inherent parasitic effects.

Dedicated low-power modes, such as stand-by mode, provide very low quiescent current during power-up of the device. In stand-by mode the typical quiescent current on V_{CC} is less than 10 µA while the device can still wake up by a bus signal on the HS CAN bus.

Fail-safe features, such as overtemperature protection, output current limitation or the TxD time-out feature are designed to protect the TLE9351SJ and the external circuitry from irreparable damage.

Type	Package	Marking
TLE9351SJ	PG-DSO-8	9351

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1 Block diagram

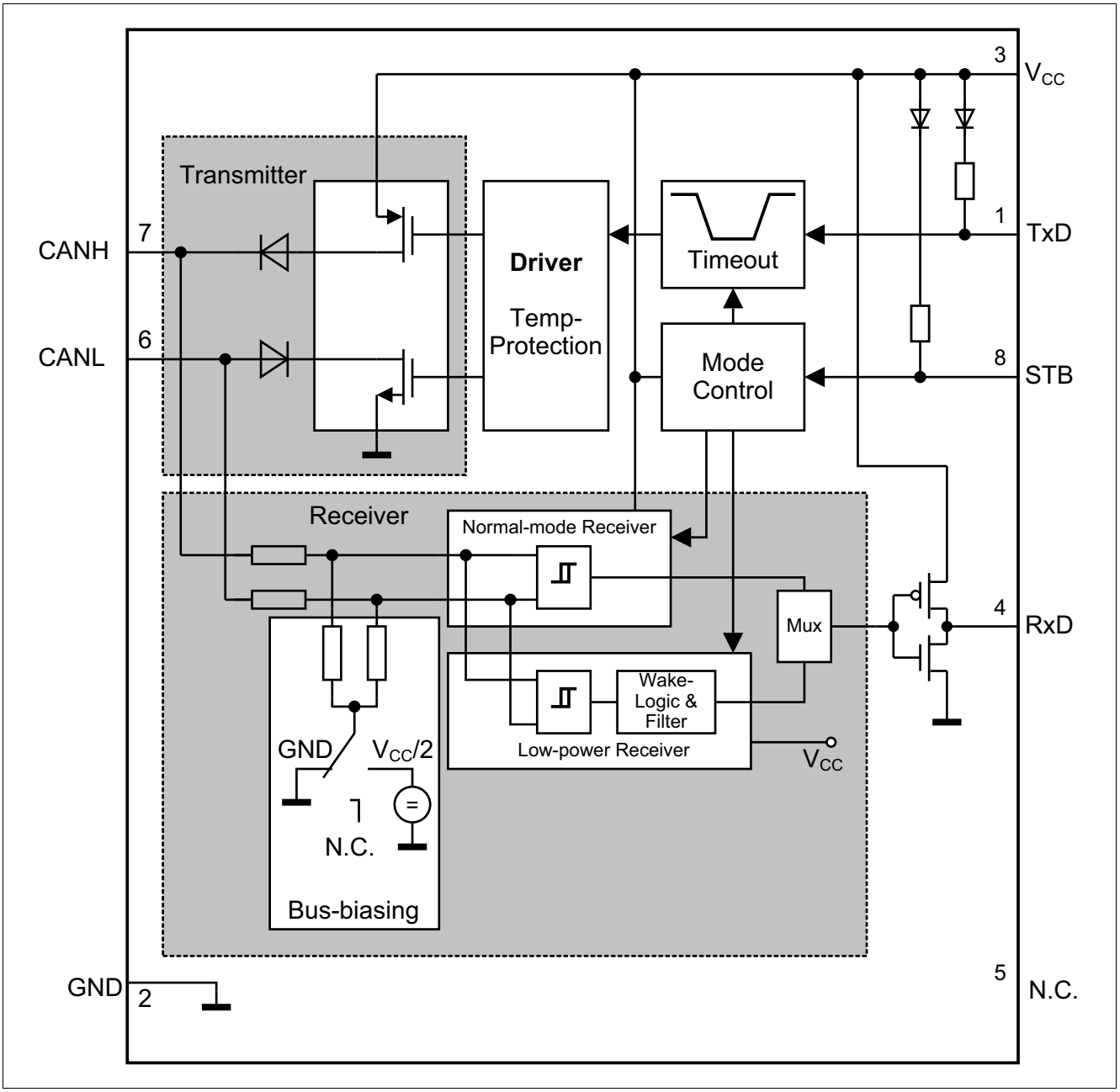


Figure 1 Block diagram

2 Pin configuration

2.1 Pin assignment

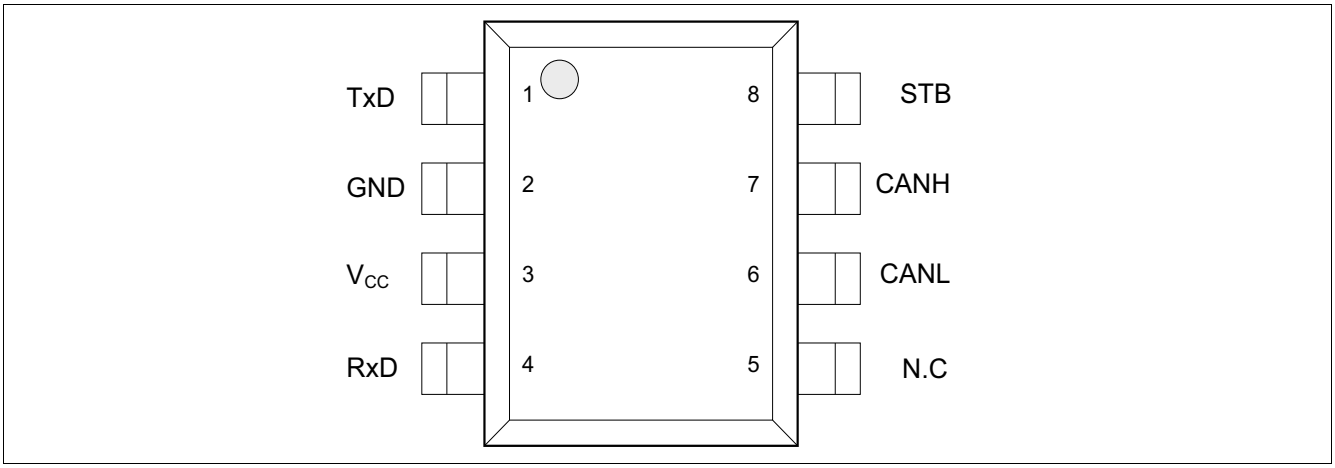


Figure 2 Pin configuration

2.2 Pin definitions

Table 1 Pin definitions and functions

Pin No.	Symbol	Function
1	TxD	**Transmit data input;** Internal pull-up to V_{CC}, "low" for dominant state.
2	GND	**Ground**
3	V_{CC}	**Transmitter supply voltage;** A decoupling capacitor of 1 µF to GND is recommended.
4	RxD	**Receive data output;** "Low" in dominant state.
5	N.C.	**Not Connected;** This pin is without function, not connected internally.
6	CANL	**CAN bus low level I/O;** Bus level on the CANL input/output.
7	CANH	**CAN bus high level I/O;** Bus level on the CANH input/output.
8	STB	**Stand-by input;** Internal pull-up to V_{CC}, "low" for normal-operating mode.

3 General product characteristics

3.1 Absolute maximum ratings

Table 2 Absolute maximum ratings voltages, currents and temperatures[1)]

All voltages with respect to ground; positive current flowing into pin;
(unless otherwise specified)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Voltages							
Transmitter supply voltage	V_{CC}	-0.3	–	6.0	V	–	P_7.1.1
CANH and CANL DC voltage versus GND	V_{CANH}	-40	–	40	V	–	P_7.1.3
Differential voltage between CANH and CANL	V_{CAN_Diff}	-40	–	40	V	–	P_7.1.4
Voltage at the digital input pins: STB, TxD	V_{MAX_IO}	-0.3	–	6.0	V	–	P_7.1.5
Voltage at the digital output pin: RxD	V_{MAX_RxD}	-0.3	–	V_{CC} +0.3	V	–	P_7.1.9
Currents							
RxD output current	I_{RxD}	-5	–	5	mA	–	P_7.1.6
Temperatures							
Junction temperature	T_j	-40	–	150	°C	–	P_7.1.7
Storage temperature	T_S	-55	–	150	°C	–	P_7.1.8
ESD immunity							
ESD immunity at CANH, CANL versus GND	$V_{ESD_HBM_CAN}$	-10	–	10	kV	HBM; (100 pF via 1.5 kΩ)[2)]	P_7.1.10
ESD immunity at all other pins	$V_{ESD_HBM_ALL}$	-2	–	2	kV	HBM; (100 pF via 1.5 kΩ)[2)]	P_7.1.11
ESD immunity corner pins	$V_{ESD_CDM_CP}$	-750	–	750	V	CDM[3)]	P_7.1.14
ESD immunity all other pins	$V_{ESD_CDM_OP}$	-500	–	500	V	CDM[3)]	P_7.1.12

1) Not subject to production test, specified by design.
2) ESD susceptibility, Human Body Model (HBM) according to ANSI/ESDA/JEDEC JS-001.
3) ESD susceptibility, Charge Device Model (CDM) according to ANSI/ESDA/JEDEC JS-002.

Note: Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as outside normal-operating range. Protection functions are not designed for continuous repetitive operation.

3.2 Functional range

Table 3 Functional range

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Supply voltages							
Transmitter supply voltage	V_{CC}	4.75	–	5.25	V	–	P_7.2.1
Thermal parameters							
Junction temperature	T_j	-40	–	150	°C	1)	P_7.2.3

1) Not subject to production test, specified by design.

Note: Within the functional range the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the related electrical characteristics table.

3.3 Thermal resistance

*Note: This thermal data was generated in accordance with JEDEC JESD51 standards. For more information, please visit **www.jedec.org**.*

Table 4 Thermal resistance[1)]

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Thermal resistance							
Junction to ambient PG-DSO-8	R_{thJA_DSO8}	–	120	–	K/W	2)	P_7.3.2
Thermal shutdown (junction temperature)							
Thermal shutdown temperature, rising	T_{JSD}	170	180	190	°C	temperature falling: minimum 150°C	P_7.3.3
Thermal shutdown hysteresis	ΔT	5	10	20	K		P_7.3.4

1) Not subject to production test, specified by design

2) Specified R_{thJA} value is according to JEDEC JESD51-2,-7 at natural convection on FR4 2s2p board. The product was simulated on a 76.2 × 114.3 × 1.5 mm^3 board with two inner copper layers (2 × 70µm Cu, 2 × 35µm Cu).

4 High speed CAN functional description

HS CAN is a serial bus system that connects microcontrollers, sensors and actuators for real-time control applications. ISO 11898 describes the use of the Controller Area Network (CAN) within road vehicles. According to the 7-layer OSI reference model the physical layer of a HS CAN bus system specifies the data transmission from one CAN node to all other CAN nodes available within the network. The physical layer specification of a CAN bus system includes all electrical specifications of a CAN. The CAN transceiver is part of the physical layer specification. The TLE9351SJ is a high speed CAN transceiver with a dedicated bus wake-up function according to ISO 11898-2:2016.

4.1 High speed CAN physical layer

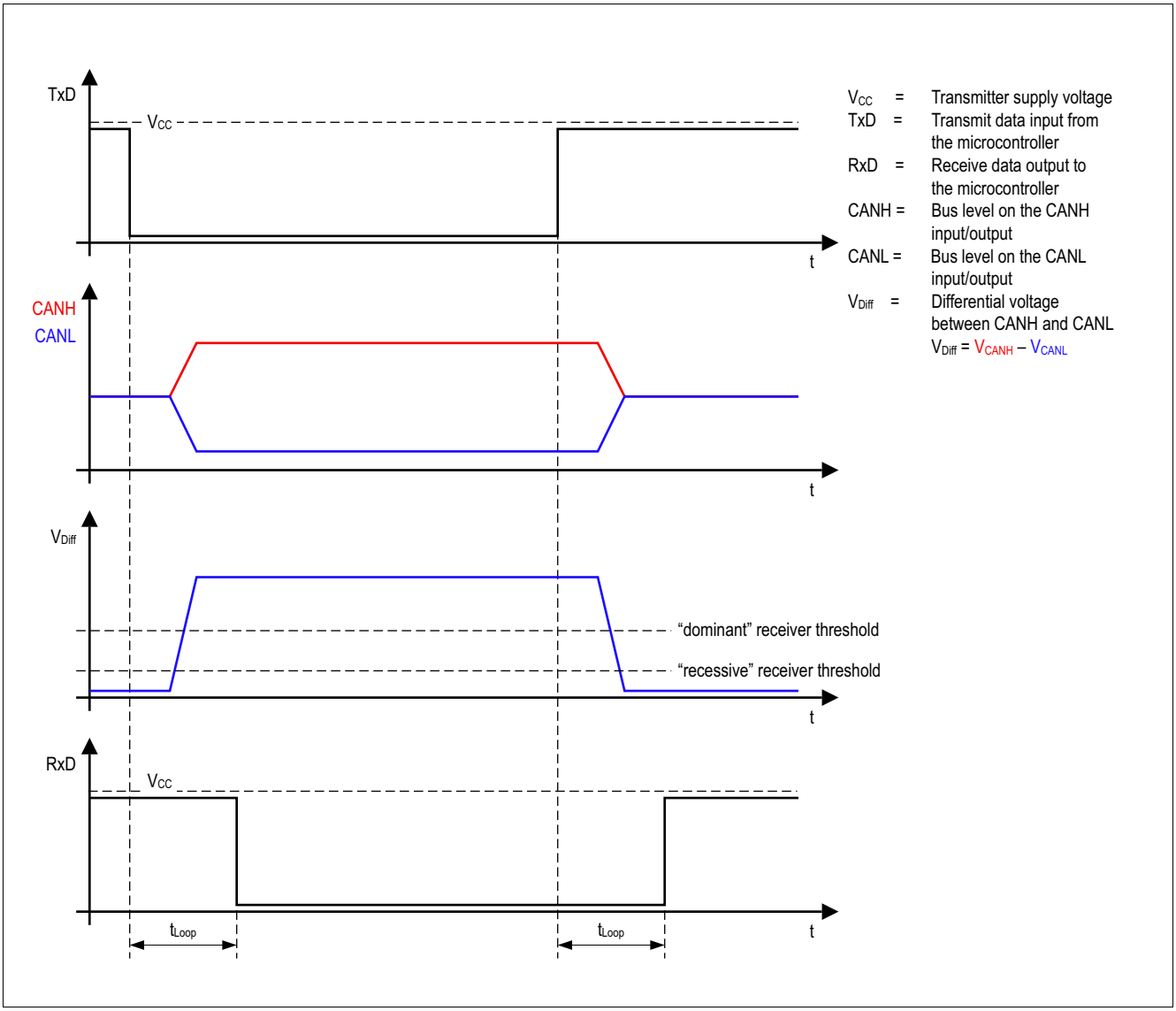


Figure 3 High speed CAN bus signals and logic signals

The TLE9351SJ operates as an interface between the CAN controller and the physical bus medium. A HS CAN is a two wire differential network which allows data transmission rates up to 5 MBit/s. The characteristics for a HS CAN are the two signal states on the CAN bus: dominant and recessive (see **Figure 3**).

The CANH and CANL pins are the interface to the CAN bus and both pins operate as an input and output simultaneously. The RxD and TxD pins are the interface to the microcontroller. The pin TxD is the serial data input from the CAN controller, the RxD pin is the serial data output to the CAN controller. As shown in **Figure 1**, the TLE9351SJ includes a receiver and a transmitter unit, allowing the transceiver to send data to the bus medium and monitor the data from the bus medium at the same time. The TLE9351SJ converts the serial data stream which is available on the transmit data input TxD, into a differential output signal on the CAN bus, provided by the CANH and CANL pins. The receiver stage of the TLE9351SJ monitors the data on the CAN bus and converts them to a serial, single-ended signal on the RxD output pin. A "low" signal on the TxD pin creates a dominant signal on the CAN bus, followed by a logical "low" signal on the RxD pin (see **Figure 3**). The feature of broadcasting data to the CAN bus and listening to the data traffic on the CAN bus simultaneously is essential to support the bit-to-bit arbitration within CAN.

ISO 11898-2:2016 specifies the voltage levels for HS CAN transceivers. Whether a data bit is dominant or recessive depends on the voltage difference between the CANH and CANL pins ($V_{Diff} = V_{CANH} - V_{CANL}$).

To transmit a dominant signal to the CAN bus the amplitude of the differential signal V_{Diff} is higher than or equal to 1.5 V. To receive a recessive signal from the CAN bus the amplitude of the differential V_{Diff} is lower than or equal to 0.5 V.

In partially-supplied high speed CAN the bus nodes of one common network have different power supply conditions. Some nodes are connected to the power supply, while other nodes are disconnected from the power supply and in power-down state. Regardless of whether the CAN bus subscriber is supplied or not, each subscriber connected to the common bus media must not interfere with the communication. The TLE9351SJ is designed to support partially-supplied networks. In power-down state, the receiver input resistors are switched off and the transceiver input has a high resistance.

For permanently supplied ECUs, the HS CAN transceiver TLE9351SJ provides a stand-by mode. In stand-by mode, the power consumption of the TLE9351SJ is optimized to a minimum, while the device is still able to recognize wake-up patterns on the CAN bus and signal the wake-up event to the external microcontroller.

The voltage level on the digital input TxD and the digital output RxD is determined by the power supply level at the V_{CC} pin. Depending on the voltage level at the V_{CC} pin, the signal levels on the logic pins (STB, TxD and RxD) are compatible with microcontrollers having a 5 V I/O supply.

5 Modes of operation

The TLE9351SJ supports the following modes of operation):

- Normal-operating mode
- Stand-by mode

The mode selection input pin STB triggers mode changes. If a wake-up event occurs on the HS CAN bus, then the device indicates that on the RxD output pin in stand-by mode, but it does not trigger a mode change. An power down event on the supply V_{CC} powers down the device.

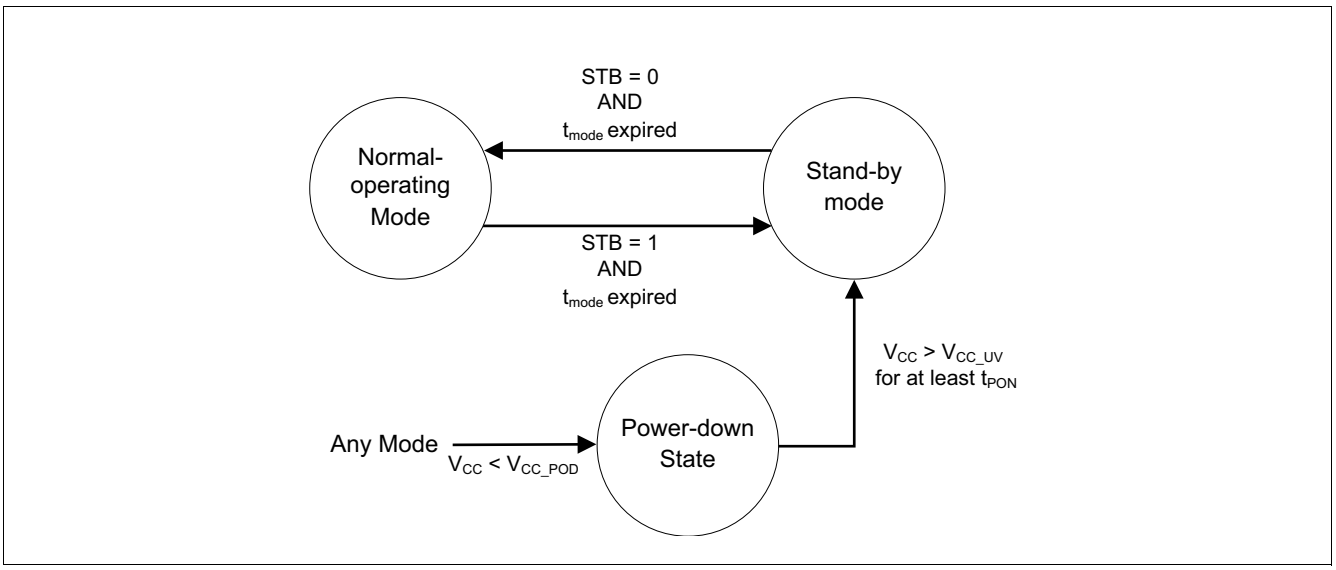


Figure 4 Mode state diagram

5.1 Normal-operating mode

In normal-operating mode all functions of the device are available and the device is fully functional. Data can be received from the HS CAN bus as well as transmitted to the HS CAN bus.

- The transmitter is enabled and drives the serial data stream on the TxD input pin to the bus pins CANH and CANL.
- The receiver is enabled and converts the signal from the bus to a serial data stream on the RxD output pin.
- The bus biasing is active.
- The TxD time-out function is enabled (see **Chapter 6.4**).
- The overtemperature protection is enabled (see **Chapter 6.6**).
- The undervoltage detection on V_{CC} is enabled (see **Chapter 6.3**).

The device enters normal-operating mode by setting the mode selection pin STB to "low", see **Figure 4**. Normal-operating mode can be entered if the device supply $V_{CC}$is higher than V_{CC_POD}. The device enters normal-operating mode after t_{mode} expires.

Note: If the device recognizes a recessive signal on the TxD input pin during a mode change from any mode to normal-operating mode, then it enables the transmit path after the mode change.
If the device recognizes a a dominant signal on the TxD input pin during a mode change to normal-operating mode, then it keeps the transmit path disabled and it blocks the dominant signal in order to not disturb the bus communication . As soon as the device recognizes a recessive signal on the TxD input pin, it enables the transmit path again.

5.2 Stand-by mode

The stand-by mode is a low power mode of the TLE9351SJ. In stand-by mode the transceiver can neither send data to the HS CAN bus nor receive data from the HS CAN bus. In stand-by mode the current consumption is reduced to a minimum while the device can still detect a wake-up pattern (WUP) on the HS CAN Bus.

- The transmitter is disabled and the data available on the TxD input is blocked.
- The low power receiver is enabled and monitors the HS CAN bus for a valid wake-up pattern (WUP). The RxD output pin indicates the detection of a valid wake-up pattern (**Chapter 5.4**). As long as no wake-up event is detected, the default of the RxD output is "high". After detecting a wake-up, the RxD follows the bus with a certain delay (see **Figure 7**).
- TxD time-out function is disabled.
- The overtemperature protection is disabled.
- The power down detection on V_{CC} is enabled (see **Chapter 6.3**).

The stand-by mode can be entered from normal-operating mode by setting the STB pin to "high".

To enter stand-by mode the supply V_{CC} must be available ($V_{CC} > V_{CC_POD}$). The device enters stand-by mode after t_{mode} expires.

5.3 Power-down State

If the supply voltage $V_{CC} < V_{CC_POD}$, then the device powers down independently of Independent of STB (see **Figure 5**). In power-down state all functions of the device are disabled and the device is switched off. The input resistors of the receiver are disconnected. The CANH and CANL bus interface of the device is floating and acts as a high impedance input with a very low leakage current. The high impedance input does not influence the recessive level of the CAN and allows an optimized EME performance of the entire network. In power-down state the transceiver is an invisible node to the bus. t_{pon} must expire as a prerequisite for the device to exit power-down state.

- The transmitter and receiver are disabled.
- The bus biasing is connected to high impedance.
- The TxD time-out function is disabled.
- The overtemperature protection is disabled.
- The power down detection on V_{CC} is enabled .

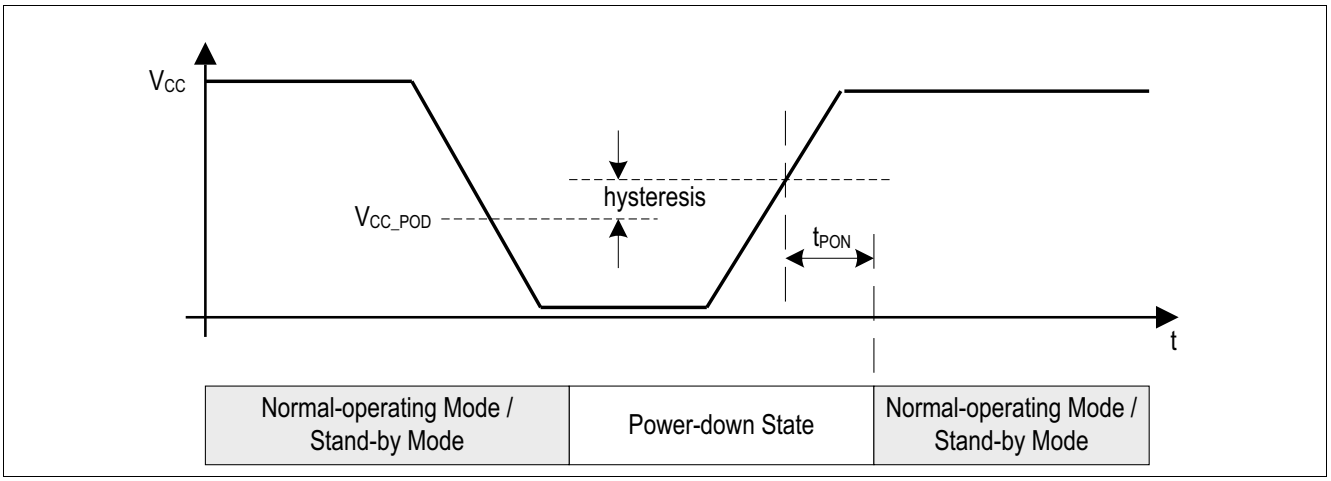


Figure 5 Power-down and power-up behavior and V_{CC}

5.4 Wake-up pattern (WUP) detection

In stand-by mode the TLE9351SJ offers the wake-up pattern (WUP) detection according to the ISO 11898-2:2016. In stand-by mode the low-power receiver monitors the activity on the CAN bus. If it detects a wake-up pattern, then it indicates the wake-up event on the RxD output pin.

In stand-by mode the device indicates a wake-up event on the HS CAN bus on the RxD output pin. The transceiver remains in its current mode of operation. The device does not perform a mode change due to the wake-up event.

The wake-up pattern contains the following sequence of signals:

- dominant with the pulse width $t > t_{Filter}$
- recessive with the pulse width $t > t_{Filter}$
- dominant with the pulse width $t > t_{Filter}$

The subsequent recessive and dominant pulses must occur within t_{Wake} to fulfill a wake-up pattern. t_{Wake}starts with the first valid dominant pulse that has a pulse width > t_{Filter}.

See **Figure 6**.

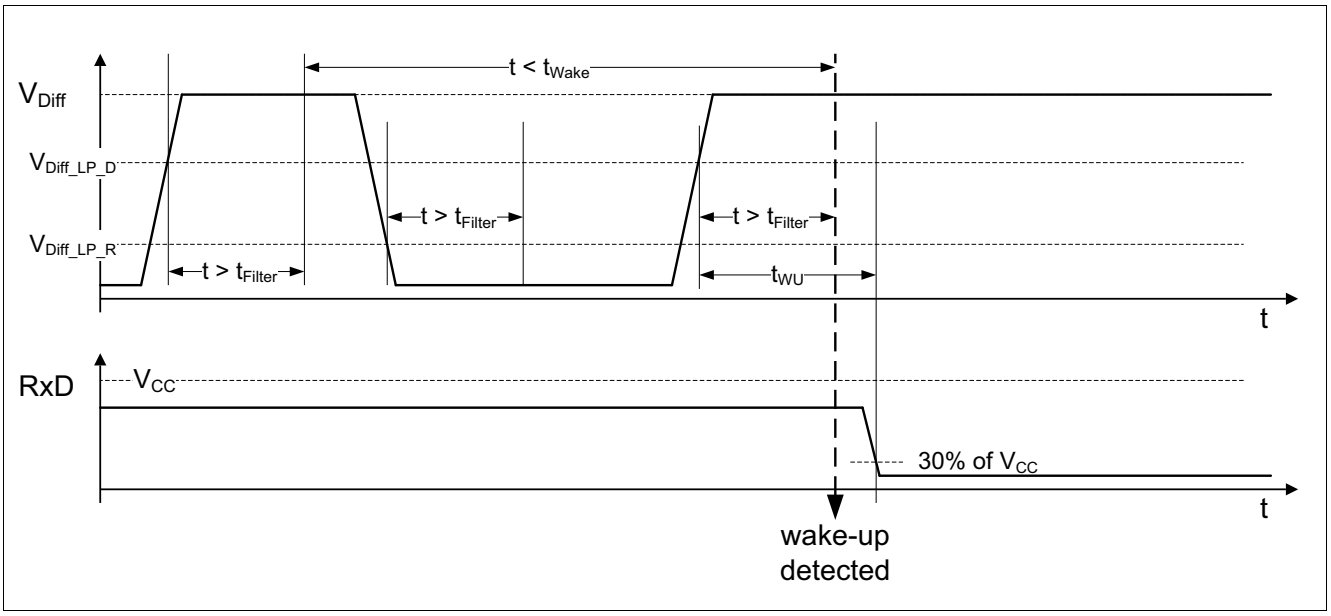


Figure 6 Wake-up pattern (WUP)

After the device detects a wake-up event the RxD output follows the CANH/CANL input pins. Dominant and recessive signals are indicated on the RxD output as "high" and "low" with the delay of t_{WU} as long their pulse width exceeds the filter time t_{Filter} (see also **Figure 7**).

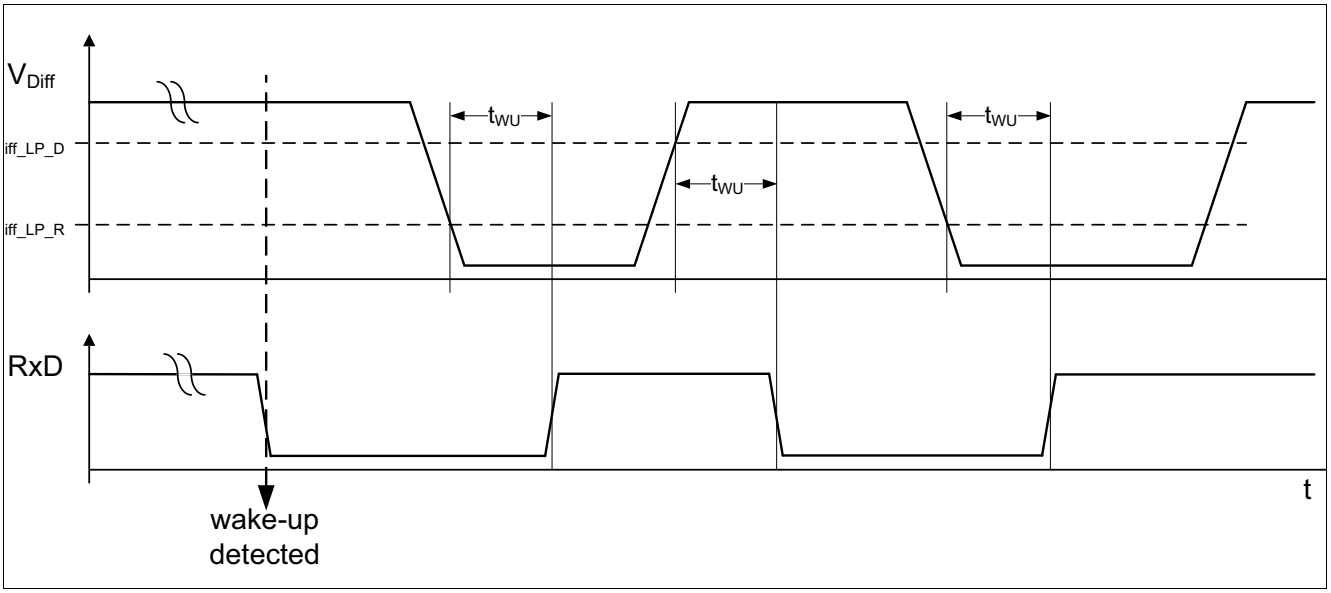


Figure 7 RxD signal after wake-up detection

6 Fail safe functions

6.1 Short circuit protection

The CANH and CANL bus outputs are short circuit proof to GND and short circuit proof to a supply voltage. The current limiting circuit is designed to protect the transceiver from damage. If the device heats up due to a continuous short on the CANH or CANL, then the internal overtemperature protection switches off the bus transmitter.

6.2 Unconnected logic pins

All logic input pins have an internal pull-up resistor to V_{CC}. If the V_{CC} supply is active and the logical pins are open, the device enters the stand-by mode by default.

6.3 V_{CC} undervoltage

If the transmitter supply is in undervoltage condition $V_{CC} < V_{CC_UV}$, then the device might not be able to provide the correct bus levels on the CANH and CANL output pins. During this time the transmitter is blocked in normal-operating mode, to avoid any interference with the network.

If the transceiver supply is in power down condition $V_{CC} < V_{CC_POD}$, then the device switches to power down mode (see **Figure 5**).

During undervoltage condition $V_{CC} < V_{CC_UV}$, the bus biasing is switched to ground in normal-operating mode.

6.4 TxD time-out feature

The TxD time-out feature protects the CAN bus against permanent blocking in case the logical signal on the TxD pin is continuously "low". A continuous "low" signal on the TxD pin might have its root cause in a locked-up microcontroller or in a short circuit on the printed circuit board, for example.

In normal-operating mode, a "low" signal on the TxD pin for the time $t > t_{TxD}$ enables the TxD time-out feature and the device disables the transmitter (see **Figure 8**). The receiver is still active and the device continues to monitor data on the bus via the RxD output pin.

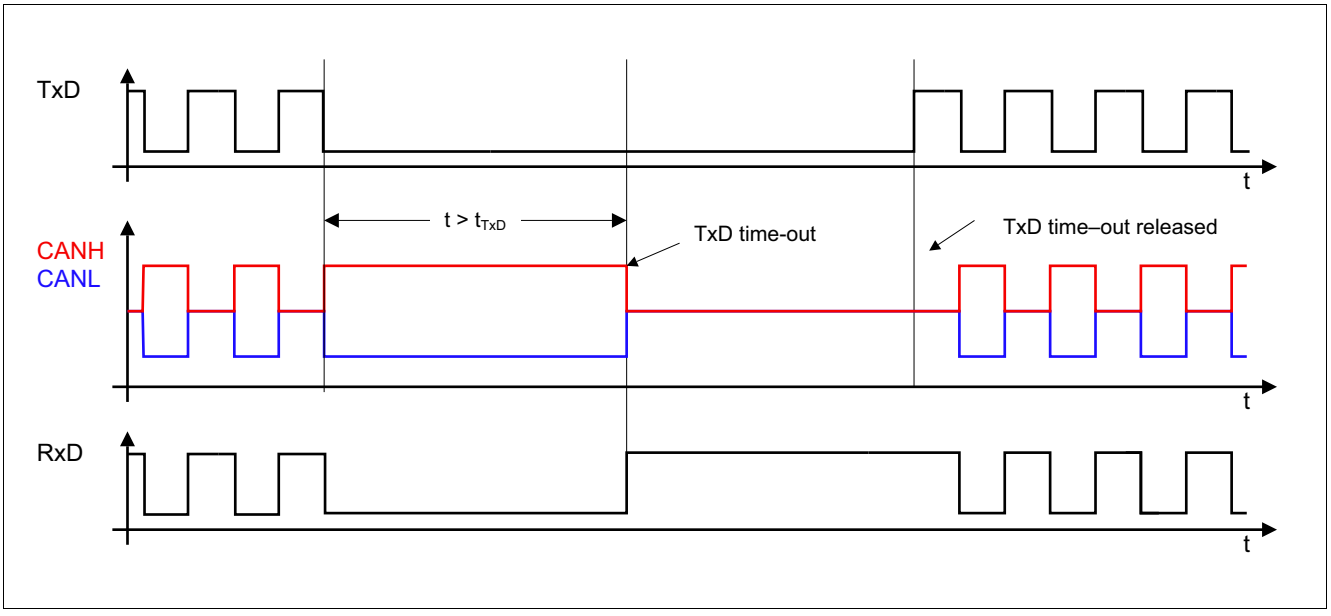


Figure 8 TxD time-out function

Figure 8 shows how the transmitter is deactivated and activated again. A permanent "low" signal on the TxD input pin activates the TxD time-out and deactivates the transmitter. To release the transmitter after a TxD time-out event, the device requires a signal change on the TxD input pin from "low" to "high".

6.5 Delay time for mode change

The device changes the mode of operation within the time window t_{Mode}. During the mode change from stand-by mode to non-low power mode the device sets the RxD output "high" permanently, so it does not reflect the status on the CANH and CANL input pins.
After the mode change is completed, the device releases the RxD output pin.

6.6 Overtemperature protection

The TLE9351SJ has an integrated overtemperature detection, which is designed to protect the device against thermal overstress of the transmitter. The overtemperature protection is only active in normal-operating mode. In case of an overtemperature condition, the temperature sensor disables the transmitter while the transceiver remains in normal-operating mode. After the device cools down it enables the transmitter again (see **Figure 9**). A hysteresis is implemented within the temperature sensor.

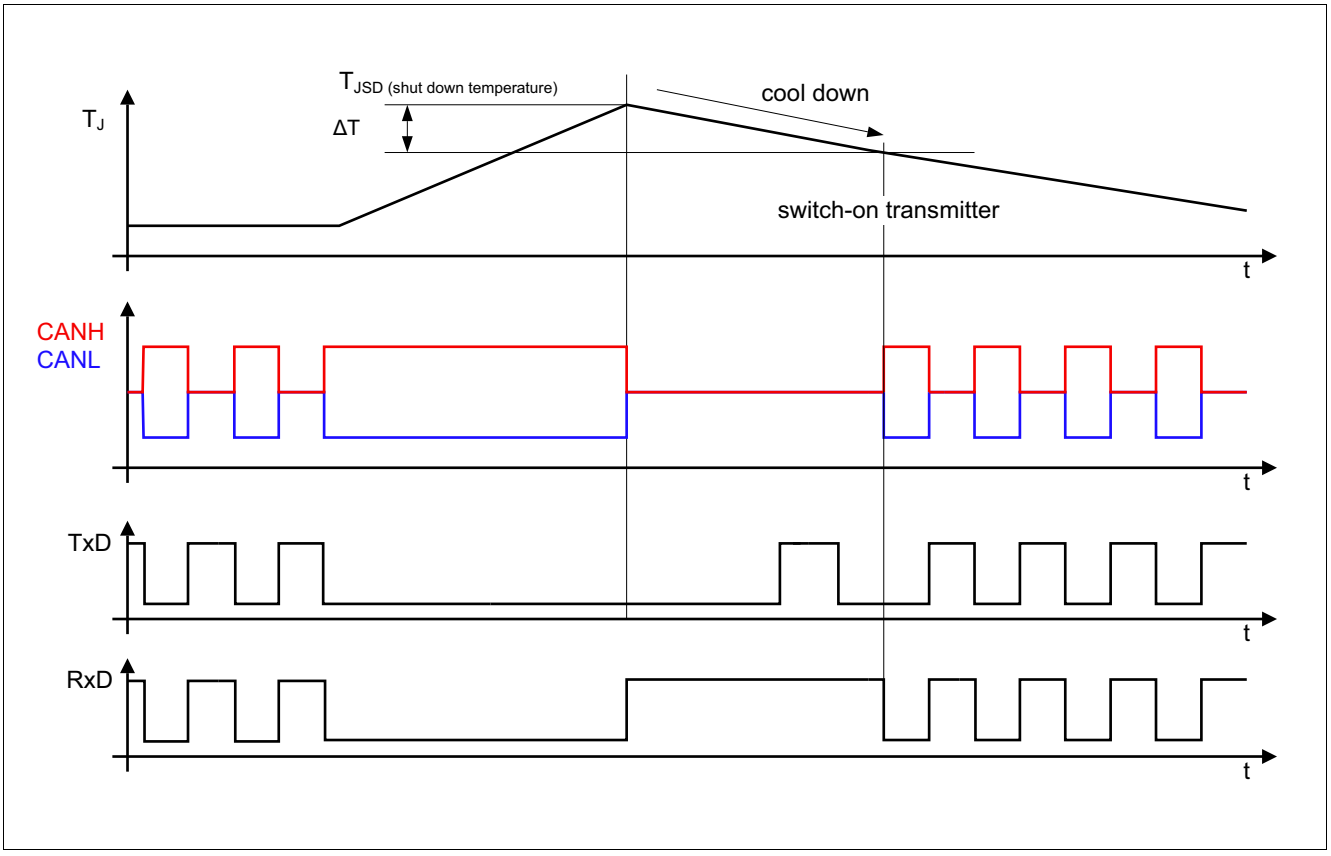


Figure 9 Overtemperature protection

7 Electrical characteristics

7.1 Power supply interface

7.1.1 Electrical characteristics current consumption

Table 5 Electrical characteristics current consumption

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Current consumption at V_{CC} normal-operating mode, recessive state	I_{CC_R}	–	1.4	4	mA	$V_{TxD} = V_{CC}$; $V = 0$ V; $V_{CANH} = V_{CANL} = V_{CC}/2$	P_8.1.1
Current consumption at V_{CC} normal-operating mode, dominant state	I_{CC_D}	–	34	48	mA	$V_{TxD} = V = 0$ V	P_8.1.2
Current consumption at V_{CC} stand-by mode	$I_{CC(STB)}$	–	5	20	µA	$V_{TxD} = V_{STB} = V_{CC}$	P_8.1.4

7.1.2 Electrical characteristics undervoltage detection

Table 6 Electrical characteristics undervoltage detection

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
V_{CC} undervoltage threshold	V_{CC_UV}	3.8	4.2	4.65	V	see	P_8.1.11
V_{CC} power-down threshold	V_{CC_POD}	2.0	2.5	3.0	V	see **Figure 5**	P_8.1.17
V_{CC} delay time power-up	t_{PON}	–	40	280	µs	[1] see **Figure 5**	P_8.1.19

1) Not subject to production test, specified by design.

7.2 Electrical characteristics CAN controller interface

Table 7 Electrical characteristics CAN controller interface

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Receiver output RxD							
"High" level output current	I_{RxD_H}	–	-2.5	-1	mA	V_{RxD} = V_{CC} -0.4 V; V_{Diff} < 0.5 V	P_8.2.1
"Low" level output current	I_{RxD_L}	1	2.5	–	mA	V_{RxD} = 0.4 V; V_{Diff} > 0.9 V	P_8.2.2
Transmission input TxD							
"High" level input voltage	V_{TxD_H}	0.7 × V_{CC}	–	6.0	V	recessive state	P_8.2.3
"Low" level input voltage	V_{TxD_L}	-0.3	–	0.3 × V_{CC}	V	dominant state	P_8.2.4
Internal pull-up resistor TxD	R_{TxD}	35	55	70	kΩ	–	P_8.2.7
Input capacitance	C_{TxD}	–	–	10	pF	1)	P_8.2.8
TxD permanent dominant time-out	t_{TxD}	1	2.3	4	ms	normal-operating mode	P_8.2.9
Stand-by input STB							
"High" level input voltage	V_{STB_H}	0.7 × V_{CC}	–	6.0	V	stand-by mode	P_8.2.13
"Low" level input voltage	V_{STB_L}	-0.3	–	0.3 × V_{CC}	V	normal-operating mode	P_8.2.14
Internal pull-up resistor STB	R_{STB}	35	55	70	kΩ	–	P_8.2.16
Input capacitance	$C_{(STB)}$	–	–	10	pF	1)	P_8.2.20

1) Not subject to production test, specified by design.

7.3 Electrical characteristics receiver

Table 8 Electrical characteristics receiver

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Differential range dominant normal-operating mode	$V_{Diff_D_Range}$	0.9	–	8.0	V	1) -12 V ≤ V_{CMR} ≤ 12 V	P_8.3.3
Differential range recessive normal-operating mode	$V_{Diff_R_Range}$	-3.0	–	0.5	V	1) -12V ≤ V_{CMR} ≤ 12 V	P_8.3.5
Differential range dominant stand-by mode	$V_{Diff_D_STB_Range}$	1.15	3.0	8.0	V	1) -12 V ≤ V_{CMR} ≤ 12 V	P_8.3.7
Differential range recessive Stand-by mode	$V_{Diff_R_STB_Range}$	-3.0	0	0.4	V	1) -12 V ≤ V_{CMR} ≤ 12 V	P_8.3.9
Common mode range	CMR	-12	–	12	V	–	P_8.3.11
Single ended internal resistance	R_{CAN_H}, R_{CAN_L}	6	40	50	kΩ	1) recessive state; -2 V ≤ V_{CANH} ≤ 7 V; -2 V ≤ V_{CANL} ≤ 7 V	P_8.3.12
Differential internal resistance	R_{Diff}	12	80	100	kΩ	1) recessive state; -2 V ≤ V_{CANH} ≤ 7 V; -2 V ≤ V_{CANL} ≤ 7 V	P_8.3.14
Input resistance deviation between CANH and CANL	ΔR_i	-3	–	3	%	1) recessive state; V_{CANH} = V_{CANL} = 5 V	P_8.3.16
Input capacitance CANH, CANL versus GND	C_{In}	–	–	40	pF	1)2) recessive state; normal-operating mode	P_8.3.17
Differential input capacitance	C_{InDiff}	–	4	20	pF	1)2) recessive state; normal-operating mode	P_8.3.18

1) Not subject to production test, specified by design.
2) S2P-Method; f = 10 MHz.

7.4 Electrical characteristics transmitter

Table 9 Electrical characteristics transmitter

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
CANL, CANH recessive output voltage normal-operating mode	$V_{CANL,H}$	2.0	2.5	3.0	V	V_{TxD} = V_{CC}; no load	P_8.4.1
CANH, CANL recessive output voltage difference normal-operating mode	$V_{Diff_R_NM}$ = V_{CANH} - V_{CANL}	-500	-10	50	mV	V_{TxD} = V; no load	P_8.4.2
CANL dominant output voltage normal-operating mode	V_{CANL}	0.5	1.5	2.25	V	V_{TxD} = 0 V; 50 Ω < R_L < 65 Ω	P_8.4.3
CANH dominant output voltage normal-operating mode	V_{CANH}	2.75	3.4	4.5	V	V_{TxD} = 0 V; 50 Ω < R_L < 65 Ω	P_8.4.4
Differential voltage dominant normal-operating mode V_{Diff} = V_{CANH} - V_{CANL}	$V_{Diff_D_NM}$	1.5	1.9	2.5	V	V_{TxD} = 0 V; 50 Ω < R_L < 65 Ω	P_8.4.5
Differential voltage dominant extended bus load normal-operating mode	$V_{Diff_EXT_BL}$	1.4	1.9	3.3	V	V_{TxD} = 0 V; 45 Ω < R_L < 70 Ω	P_8.4.6
Differential voltage dominant high extended bus load normal-operating mode	$V_{Diff_HEXT_BL}$	1.5	3.5	5.0	V	[1] V_{TxD} = 0 V; R_L = 2240Ω; static behavior	P_8.4.7
CANH, CANL recessive output voltage difference stand-by mode	V_{Diff_STB}	-0.2	0.001	0.2	V	no load	P_8.4.8
CANL, CANH recessive output voltage stand-by mode	V_{CANL,H_STB}	-0.1	0.01	0.1	V	no load	P_8.4.9
Driver symmetry (V_{SYM} = V_{CANH} + V_{CANL})	V_{SYM}	0.9 × V_{CC}	1.0 × V_{CC}	1.1 × V_{CC}	V	[1] [2] C_1 = 4.7 nF	P_8.4.10
CANL short circuit current	I_{CANLsc}	-115	90	115	mA	[1] -3 V < $V_{CANLshort}$ < 18 V; t < t_{TxD}; V_{TxD} = 0 V	P_8.4.11
CANH short circuit current	I_{CANHsc}	-115	-90	115	mA	[1] -3 < $V_{CANHshort}$ < 18 V; t < t_{TxD}; V_{TxD} =0 V	P_8.4.13
Leakage current, CANH	$I_{CANH,lk}$	-5	1	5	µA	V_{CC} = 0 V; 0 V < V_{CANH} ≤ 5 V; V_{CANH} = V_{CANL};	P_8.4.19

Table 9 Electrical characteristics transmitter (Continued)

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Leakage current, CANL	$I_{CANL,lk}$	-5	1	5	µA	V_{CC} = 0 V; 0 V < V_{CANL} ≤ 5 V; V_{CANH} = V_{CANL}	P_8.4.20
CANH, CANL output voltage difference slope, recessive to dominant	$V_{diff_slope_rd}$	–	42	70	V/µs	[1] 30% to 70% of measured differential bus voltage, C_2 = 100 pF, R_L = 60 Ω, 4.75 V < V_{CC} < 5.25 V	P_8.4.21
CANH, CANL output voltage difference slope, dominant to recessive	$V_{diff_slope_dr}$	–	42	70	V/µs	[1] 70% to 30% of measured differential bus voltage, C_2 = 100 pF, R_L = 60 Ω, 4.75 V < V_{CC} < 5.25 V	P_8.4.22

1) Not subject to production test, specified by design.

2) V_{SYM} is observed during dominant and recessive state and also during the transition from dominant to recessive state and vice versa, while TxD is stimulated by a square wave signal with a frequency of 1 MHz.

7.5 Electrical characteristics dynamic transceiver parameters

Table 10 Electrical characteristics dynamic transceiver parameters

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Propagation delay TxD-to-RxD	t_{Loop}	80	150	255	ns	C_1 = 0 pF, C_2 = 100 pF, C_{RxD} = 15 pF; (see **Figure 11**)	P_8.5.1
Propagation delay increased load TxD-to-RxD	t_{Loop_150}	80	180	330	ns	C_1 = 0 pF, C_2 = 100 pF, C_{RxD} = 15 pF, R_L = 150 Ω [1]	P_8.5.2
Propagation delay TxD to bus "low" to dominant	$t_{d(L)_T}$	30	70	140	ns	C_1 = 0 pF, C_2 = 100 pF, C_{RxD} = 15 pF; (see **Figure 11**)	P_8.5.3
Propagation delay TxD to bus "high" to recessive	$t_{d(H)_T}$	30	90	140	ns	C_1 = 0 pF, C_2 = 100 pF, C_{RxD} = 15 pF; (see **Figure 11**)	P_8.5.4
Propagation delay bus to RxD dominant to "low"	$t_{d(L)_R}$	30	90	140	ns	C_{RxD} = 15 pF, Independent of t_{Bit}; (see **Figure 11**)	P_8.5.5
Propagation delay bus to RxD recessive to "high"	$t_{d(H)_R}$	30	100	140	ns	C_{RxD} = 15 pF, Independent of t_{Bit}; (see **Figure 11**)	P_8.5.6
Delay Times							
Delay time for mode change	t_{Mode}	–	12	20	µs	[1]	P_8.5.7
CAN activity filter time	t_{Filter}	0.5	1.2	1.8	µs	see **Figure 6**	P_8.5.10
Bus wake-up timeout	t_{Wake}	0.8	1.5	10	ms	[1] see **Figure 6**	P_8.5.11
Bus wake-up delay time	t_{WU}	–	2.5	5	µs	see **Figure 6** and **Figure 7**	P_8.5.12
CAN FD characteristics							
Received recessive bit width at 2 MBit/s	$t_{Bit(RxD)_2M}$	420	450	520	ns	C_2 = 100 pF; C_{RxD} = 15 pF; t_{Bit} = 500 ns; see **Figure 12**	P_8.5.13

Table 10 Electrical characteristics dynamic transceiver parameters (Continued)

4.75 V < V_{CC} < 5.25 V; R_L = 60 Ω; -40°C < T_j < 150°C; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Received recessive bit width at 5 MBit/s	$t_{Bit(RxD)_5M}$	120	150	220	ns	C_2 = 100 pF; C_{RxD} = 15 pF; t_{Bit} = 200 ns; see **Figure 12**	P_8.5.14
Transmitted recessive bit width at 2 MBit/s	$t_{Bit(Bus)_2M}$	455	470	510	ns	C_2 = 100 pF; C_{RxD} = 15 pF; t_{Bit} = 500 ns; see **Figure 12**	P_8.5.15
Transmitted recessive bit width at 5 MBit/s	$t_{Bit(Bus)_5M}$	155	170	210	ns	C_2 = 100 pF; C_{RxD} = 15 pF; t_{Bit} = 200 ns; see **Figure 12**	P_8.5.16
Receiver timing symmetry at 2 MBit/s $\Delta t_{Rec_2M} = t_{Bit(RxD)_2M} - t_{Bit(Bus)_2M}$	Δt_{Rec_2M}	-45	-23	15	ns	C_2 = 100 pF; C_{RxD} = 15 pF; t_{Bit} = 500 ns; see **Figure 12**	P_8.5.17
Receiver timing symmetry at 5 MBit/s $\Delta t_{Rec_5M} = t_{Bit(RxD)_5M} - t_{Bit(Bus)_5M}$	Δt_{Rec_5M}	-45	-23	15	ns	C_2 = 100 pF; C_{RxD} = 15 pF; t_{Bit} = 200 ns; see **Figure 12**	P_8.5.18

1) Not subject to production test, specified by design.

7.6 Diagrams

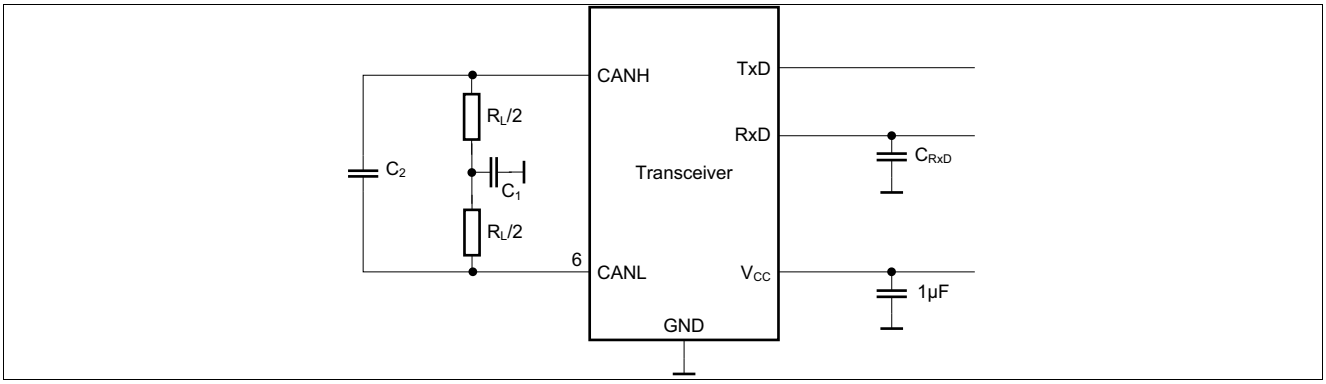


Figure 10 Test circuit

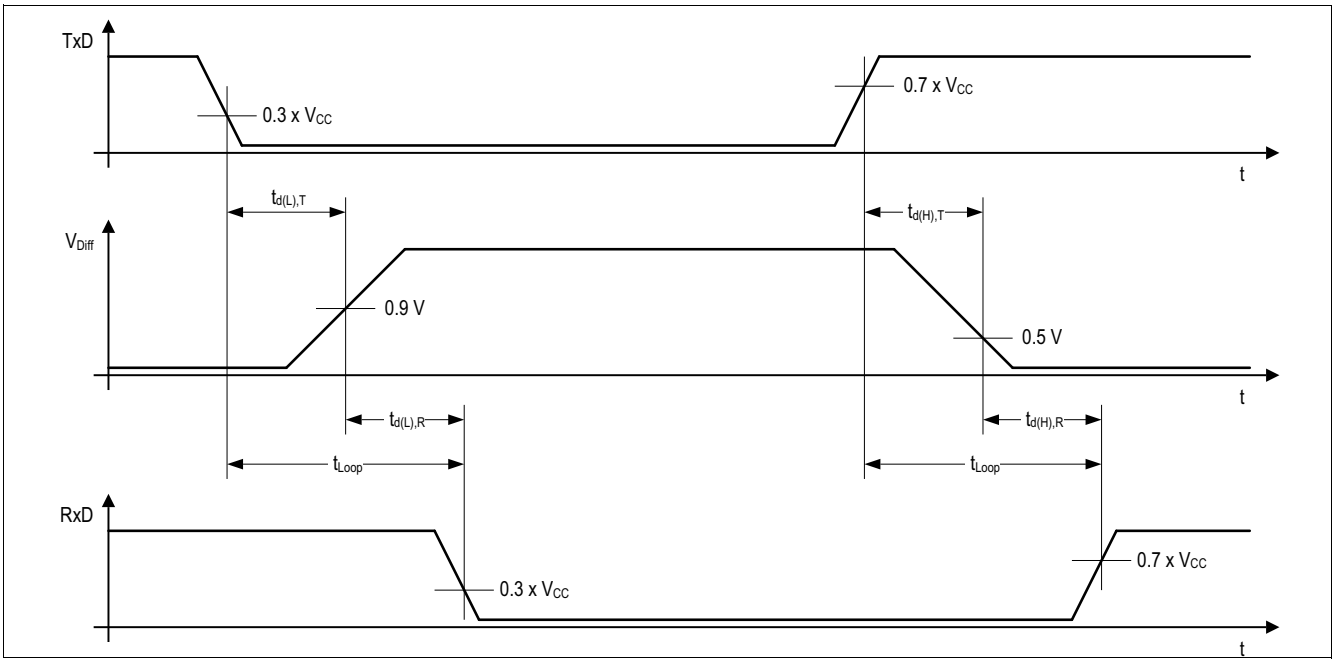


Figure 11 Timing diagrams for dynamic characteristics

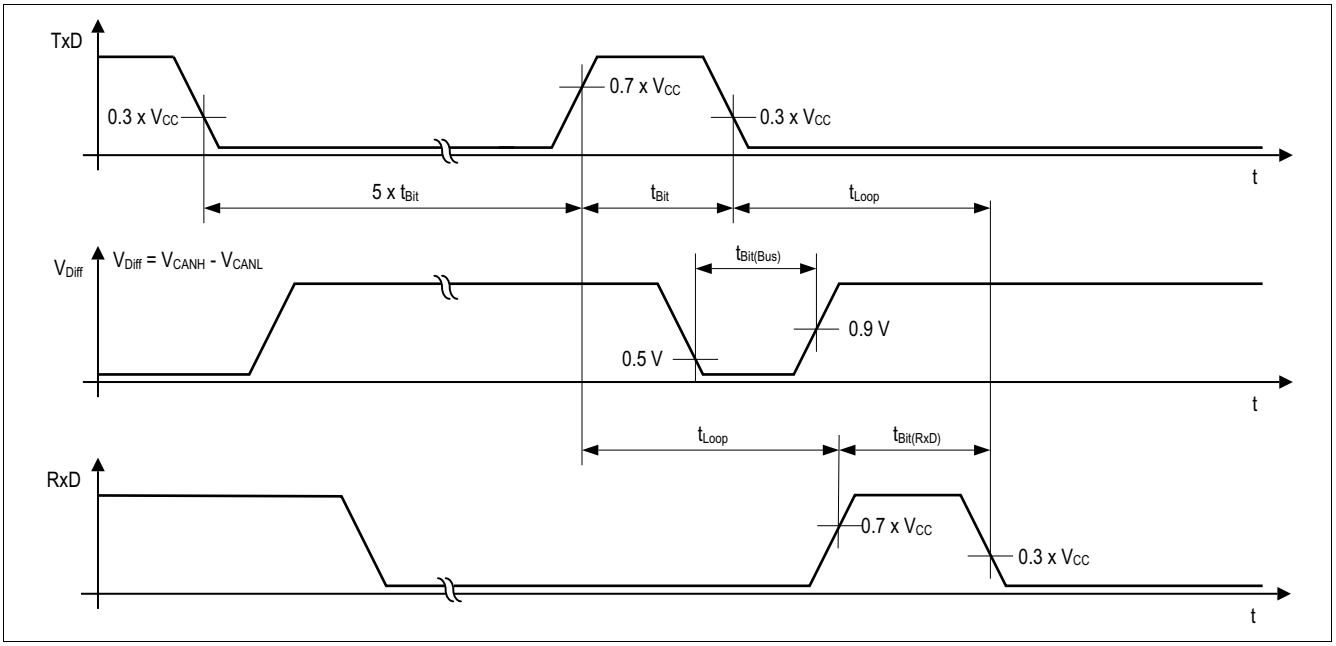


Figure 12 Recessive bit time for five dominant bits followed by one recessive bit

8 Application information

8.1 ESD robustness according to IEC 61000-4-2

Tests for ESD robustness according to IEC 61000-4-2 Gun test (150 pF, 330 Ω) have been performed. The results and test conditions are available in a separate test report.

Table 11 ESD robustness according to IEC 61000-4-2

Performed test	Result	Unit	Remarks
Electrostatic discharge voltage at pin CANH and CANL versus GND	≥ +8	kV	1) positive pulse
Electrostatic discharge voltage at pin CANH and CANL versus GND	≤ -8	kV	1) negative pulse

1) Not subject to production test. ESD susceptibility "ESD GUN" according to GIFT/ICT paper: "EMC Evaluation of CAN Transceivers, version IEC TS62228", section 4.3. (DIN EN61000-4-2)
Tested by external test facility (IBEE Zwickau).

8.2 Application example

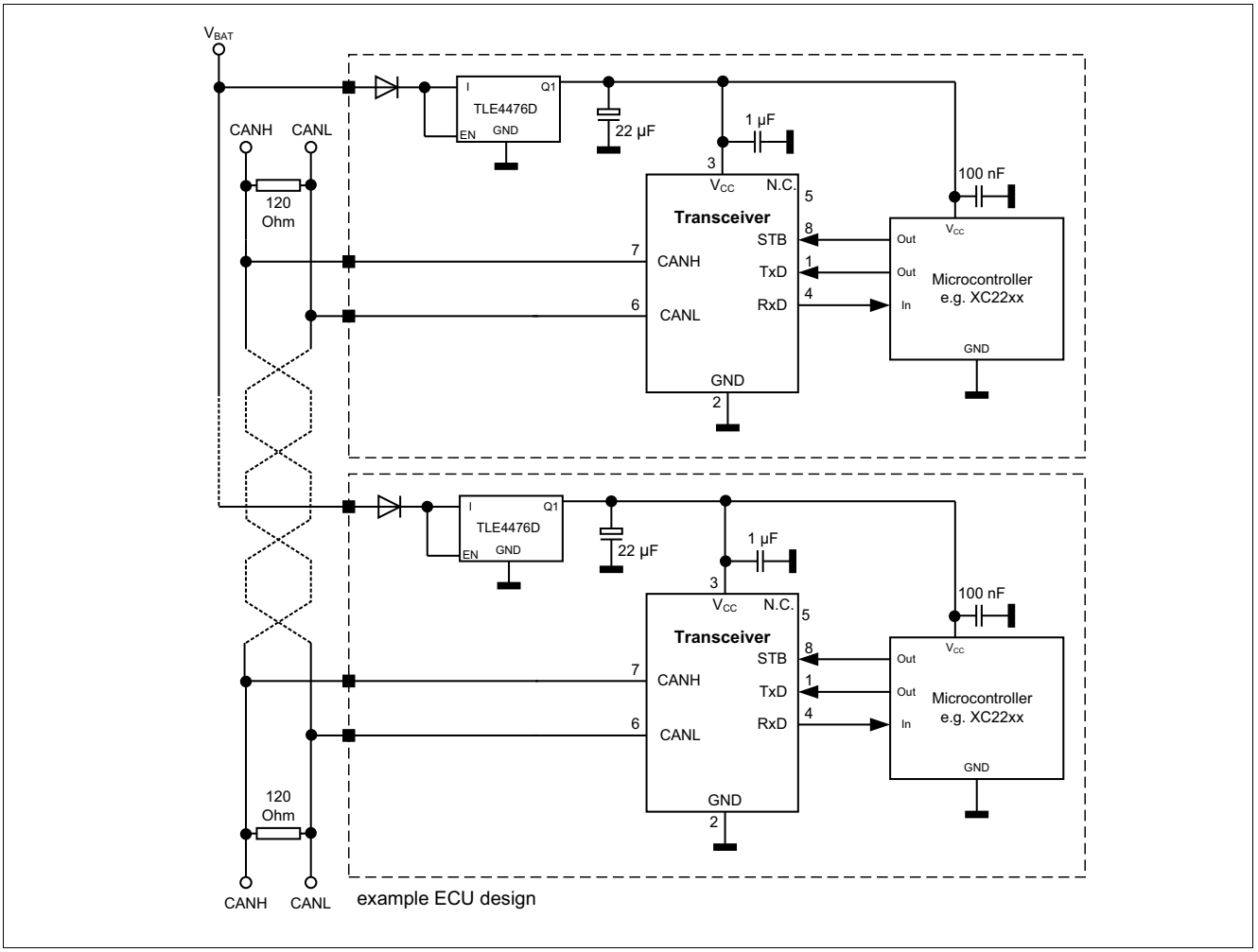
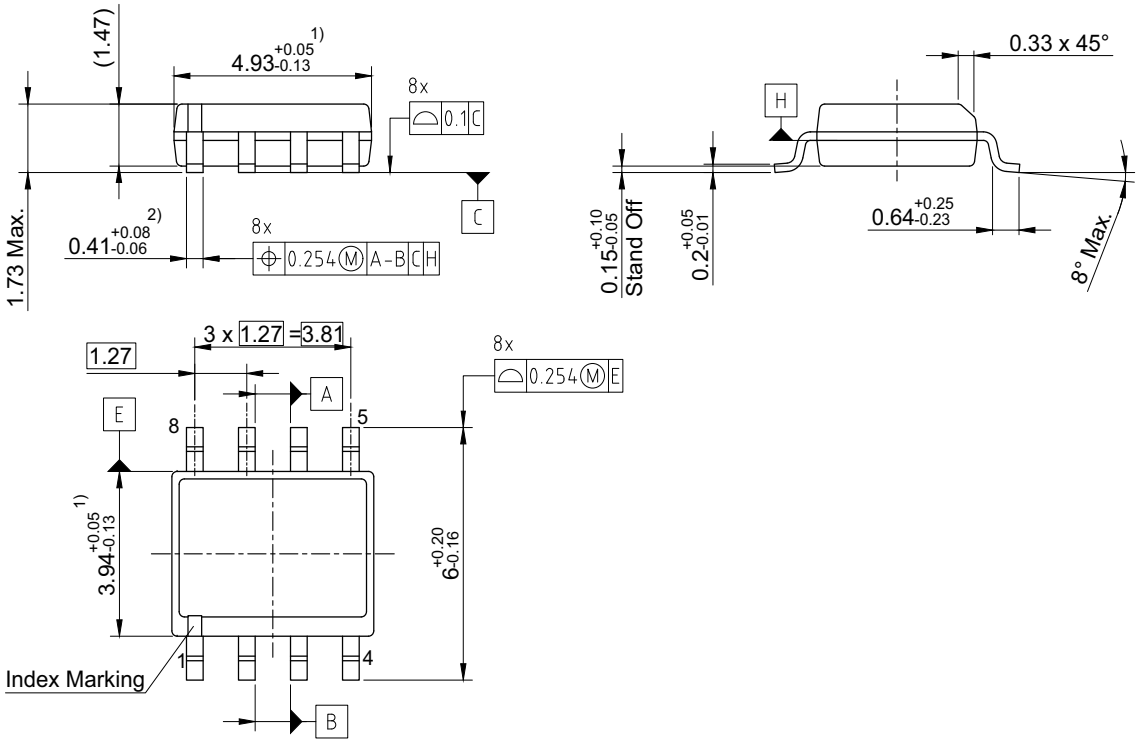


Figure 13 Application circuit

8.3 Further application information

For further information you may visit: **https://www.infineon.com/automotive-transceiver**

9 Package information



1) Does not include plastic or metal protrusion of 0.25 Max. per side
2) Does not include dambar protrusion of 0.1 Max. per side
All dimensions are in units mm
The drawing is in compliance with ISO 128-30, Projection Method 1 [ ]

Figure 14 PG-DSO-8

Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e. Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

Further information on packages

https://www.infineon.com/packages

10 Revision history

Revision	Date	Changes
1.0	2020-11-06	Datasheet created

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